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- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Typical V_{OLV} (Output Undershoot) < 0.5 V at V_{CC} = 5 V, T_A = 25°C
- Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and DIPs (JT)

description

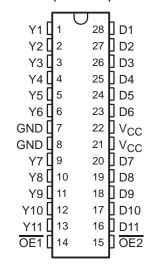
These 11-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable $(\overline{OE1} \text{ or } \overline{OE2})$ input is high, all 11 outputs are in the high-impedance state. These devices provide inverted data.

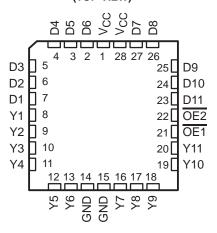
The outputs, which are designed to source or sink up to 12 mA, include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT5401 ... JT PACKAGE SN74ABT5401 ... DW PACKAGE (TOP VIEW)



SN54ABT5401 . . . FK PACKAGE (TOP VIEW)



The SN54ABT5401 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT5401 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

	INPUTS	OUTPUT	
OE1	OE2	D	Y
L	L	L	Н
L	L	Н	L
Н	X	Χ	Z
Х	Н	Χ	Z



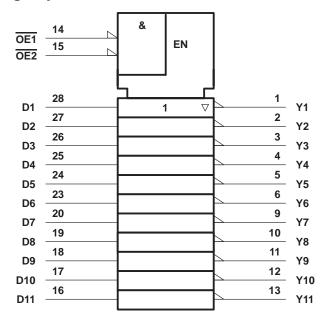
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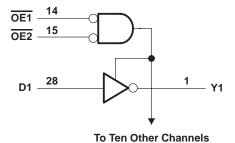
SN54ABT5401, SN74ABT5401 11-BIT LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

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logic symbol†



logic diagram (positive logic)



Pin numbers shown are for the DW and JT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	
Current into any output in the low state, I _O	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 2): DW package	78°C/W
Storage temperature range, T _{stq}	—65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 3)

				T5401	SN74AB	UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
V _{IH} High-level input voltage				1/4	2		V
V _{IL}	V _{IL} Low-level input voltage					0.8	V
VI	V _I Input voltage				0	VCC	V
IOH	IOH High-level output current					-12	mA
loL	Low-level output current		20	12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	2	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	A = 25°C	;	SN54ABT5401		SN74ABT5401			
PAI	KAMETEK	I IEST CON	MIN	TYP†	MAX	MAX MIN		MIN	MAX	UNIT		
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	3.35	3.7		3.3		3.35			
\/a		V _{CC} = 5 V,	$I_{OH} = -1 \text{ mA}$	3.85	4.2		3.8		3.85		v	
VOH		V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$				3		3.1		V	
		VCC = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.6					2.6			
\/a.		V _{CC} = 4.5 V	I _{OL} = 8 mA					0.8		0.65	V	
VOL		vCC = 4.3 v	I _{OL} = 12 mA							0.8		
V _{hys}					100						mV	
lį		$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±1		±1		±1	μΑ	
lozh		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50		50 50		μΑ		
lozL		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			- 50		- 50		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	20			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	200	50		50	μΑ	
Io		V _{CC} = 5.5 V,	V _O = 2.5 V	-25	-45	-100	25	-100	-25	-100	mA	
los [‡]		V _{CC} = 5.5 V,	VO = 0	-50		-200	2 -50	-200	-50	-200	mA	
		V _{CC} = 5.5 V,	Outputs high		5	50		50		50	μΑ	
Icc		$I_{O} = 0$,	Outputs low		36	45		45		45	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		1	50		50		50	μΑ	
	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5		
ΔI _{CC} §	Data Inputs	Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5		
C _i		V _I = 2.5 V or 0.5 V			3						pF	
Co		V _O = 2.5 V or 0.5 V			8						pF	

 $[\]dagger$ All typical values are at $V_{CC} = 5 \text{ V}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.



[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

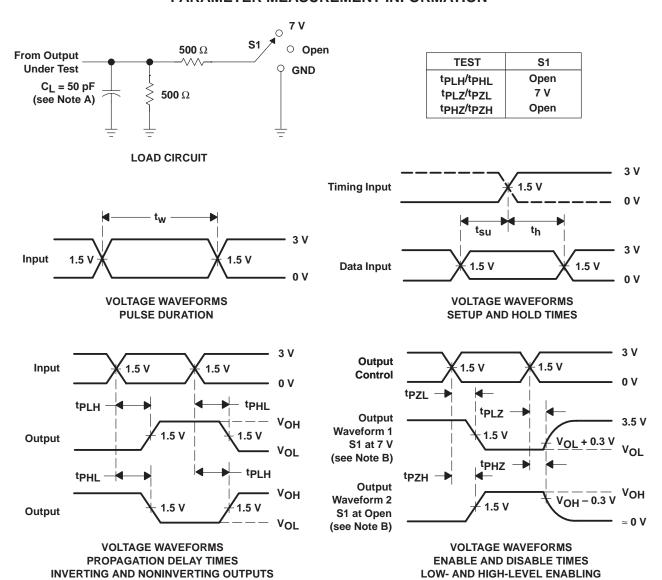
SN54ABT5401, SN74ABT5401 11-BIT LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT5401		SN74ABT5401		UNIT	
	(INFO1)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
^t PLH	D	V	2	4.5	6.1	2	47	2	6.9	ns	
^t PHL	Ь	ī	1.5	4.4	5.2	1.5	5.9	1.5	5.7	115	
^t PZH	ŌĒ	Y	2.5	5.7	6.6	2.5	8.6	2.5	8.5	ns	
^t PZL			2	4.4	5.5	\$	6.9	2	6.8	115	
^t PHZ	ŌĒ	OF V	V	1.5	3.6	4.4	7.5	5.5	1.5	5.2	no
t _{PLZ}	OE .	Y	Y	1.5	4.2	5.4	1.5	7.4	1.5	6.9	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 n
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT5401DW	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT5401DWE4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT5401DWG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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